

*Application No. 10/674209*  
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*Amendment*  
*Attorney Docket No. 011.2B-11333-US01*

**Amendments To The Claims:**

1. (Currently Amended) A polishing composition used in a polishing process for reducing haze level of wafer surface, comprising:  
  
    hydroxyethyl cellulose compounded in said composition in a quantity larger than 0.01% by weight and smaller than 3% by weight and having an average molecular weight in the range of 300,000 to 3,000,000 ;  
  
    polyethylene oxide compounded in said composition in a quantity larger than 0.005% by weight and smaller than 0.5% by weight and having an average molecular weight in the range of 30,000 to 50,000,000 ;  
  
    an alkaline compound;  
    water; and  
    silicon dioxide.
2. (Original) The polishing composition according to claim 1, wherein the total content of iron, nickel, copper, and calcium in the silicon dioxide, as measured in a 20 wt-% aqueous solution of said silicon dioxide, is 300 ppm or less.
3. (Original) The polishing composition according to claim 1, wherein the content of hydroxyethyl cellulose in the polishing composition is 0.1 to 1% by weight.
4. (Original) The polishing composition according to claim 1, wherein the content of silicon dioxide in the polishing composition is 3 to 20% by weight.
5. (Original) The polishing composition according to claim 1, wherein the alkaline compound is ammonia.

Please cancel claims 6-13.

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**Amendments To The Drawings:**

None.